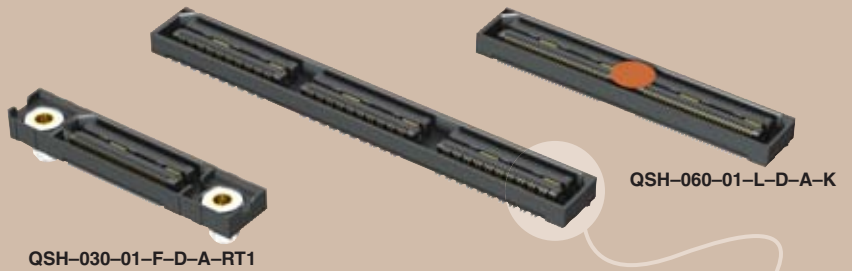




(0,50mm) .0197"

QSH SERIES

QSH-060-01-L-D-DP-A



HIGH SPEED GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QSH

Insulator Material:

Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over 50µ" (1,27µm) Ni

Current Rating:

Contact: 1.0A @ 30°C

Temperature Rise

Ground Plane: 7.8A @ 30°C

Temperature Rise

Operating Temp Range: -55°C to +125°C

Voltage Rating:

125 VAC (5mm Stack Height)

Max Cycles:

100

Unmating Force (-RT1 option):

-RT1 option increases un-mating force up to 50%

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10mm) .004" max (030-060)

(0,15mm) .006" max (090-120)

Board Stacking:

For applications requiring more than two connectors per board or four banks or more, contact ipg@samtec.com

APPLICATION SPECIFIC OPTION

- 14mm, 15mm, 22mm and 30mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
 - 30µ" (0,76µm) Gold (Specify -H plating for Data Rate cable mating applications.)
 - Edge Mount & Guide Posts
 - 150 positions per row
- Call Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.

Board Mates:
QTH

Cable Mates:

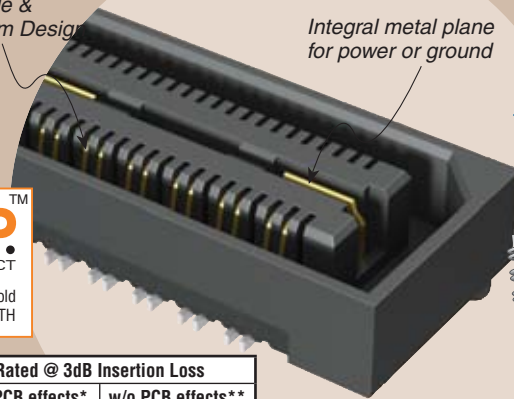
HQCD, HQDP, HFHM2

(See Application Specific note)



Blade & Beam Design

Integral metal plane for power or ground



Protocols Supported

Hypertransport™

XAUI

PCI Express®

SATA

InfiniBand™

Download app notes at:

www.samtec.com/appnote

Contact SIG @ samtec.com

for questions on protocols

QTH/QSH 5mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9 GHz / 18 Gbps	11 GHz / 22 Gbps
Differential Pair Signaling	-D	8 GHz / 16 Gbps	10.5 GHz / 21 Gbps
Differential Pair Signaling	-DP	9.5 GHz / 19 Gbps	—

*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.

Performance data for other stack heights and complete test data available at www.samtec.com?QSH or contact sig@samtec.com

ALSO AVAILABLE

Board Spacing Standoffs. See SO Series.

QSH	PINS PER ROW NO. OF PAIRS	01	PLATING OPTION	TYPE	A	OTHER OPTION
			-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails			
	-030, -060, -090, -120 (60 total pins per bank = -D)		-L = 10µ" (0,25µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails		-D = Single-Ended	-K = (8,25mm) .325" DIA Polyimide Film Pick & Place Pad
	-020, -040, -060, -080 (20 pairs per bank = -D-DP)		-C* = Electro-Polished Selective 50µ" (1,27µm) min Au over 150µ" (3,81µm) Ni on Signal Pins in contact area, 10µ" (0,25µm) min Au over 50µ" (1,27µm) Ni on Ground Plane in contact area, Matte Tin over 50µ" (1,27µm) min Ni on all solder tails		-D-DP = Differential Pair (-01 only)	-TR = Tape & Reel (-090 positions maximum)
						-RT1 = Retention Option (-090 positions maximum)
						-L = Latching Option (N/A on -060 (-D-DP), -080, -090 & -120 positions or -RT1 option)

Diagram 1: Dimensions for -D and -DP

-D = (No. of Pins per Row/30) x (20,00) .7875 + (1,27) .050

-DP = (No. of Pairs per Row/20) x (20,00) .7875 + (1,27) .050

Diagram 2: Dimensions for -01

Diagram 3: Dimensions for -RT1

Diagram 4: Dimensions for -L

QTH LEAD STYLE	MATED HEIGHT WITH QSH*
-01	(5,00) .197
-02	(8,00) .315
-03	(11,00) .433
-04	(16,00) .630
-05	(19,00) .748
-07	(25,00) .984

*Processing conditions will affect mated height.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM